



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-03-06
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32H7A3LGH6Q	57IB*480XXX	A	9996	2025-03-06
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	320	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Tin/Silver/Copper (SAC105)	Not Applicable	NAC	0	
Package designator	Package size	Number of instances	Shape	
BGA	13x13	225	Bulk solder	
Comment	Package : B04V TFBGA 13X13X1.2 225L P 0.80 MM DM00384539			

QueryList : RoHS Directive 2011/65/EU - 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
,		

QueryList : REACH-21st January 2025				Response
QUERY				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	57IB*480XXX		320.3548		6000000.0	1000000.0				
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	8.388	mg	supplier	die	Silicon (Si)	7440-21-3		7.743	mg	923105	24170.09				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.076	mg	9061	237.25				
				supplier	metallization	Copper (Cu)	7440-50-8		0.240	mg	28612	749.16				
				supplier	metallization	Nickel (Ni)	7440-02-0		0.001	mg	119	3.12				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.039	mg	4649	121.73				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.007	mg	835	21.86				
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	119	3.12				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.281	mg	33500	877.15				
				Substrate (101407459)	M-011 Other inorganic materials	73.950	mg	supplier	Core	Fibrous-Glass-Wool	65997-17-3		10.412	mg	140793.9064	32500.56
supplier	Core	Formaldehyde Polymer with (Chloromethyl)Oxirane	28906-96-9						2.650	mg	35836.58403	8272.44				
supplier	Core	Triazine	25722-66-1						2.650	mg	35836.58403	8272.44				
supplier	Core	Silicon dioxide	7631-86-9						6.478	mg	87600.53874	20221.52				
supplier	Copper Foil	Copper (Cu)	7440-50-8						22.180	mg	299932.3867	69235.75				
supplier	Soldermask (AUS320)	Cured Resin	Proprietary						12.284	mg	166110.2096	38344.52				
supplier	Soldermask (AUS320)	Phthalocyanine Blue	147-14-8						0.033	mg	440.0270453	101.57				
supplier	Soldermask (AUS320)	Organic Pigment	Proprietary						0.033	mg	440.0270453	101.57				
supplier	Soldermask (AUS320)	Silica	Proprietary						0.081	mg	1100.067613	253.94				
supplier	Soldermask (AUS320)	Barium sulfate	7727-43-7						3.384	mg	45762.81271	10563.79				
supplier	Soldermask (AUS320)	Talc	14807-96-6						0.342	mg	4620.283976	1066.54				
supplier	Soldermask (AUS320)	Antifoamer and Leveling Agent	Proprietary						0.114	mg	1540.094659	355.51				
supplier	Ni Plating	Nickel (Ni)	7440-02-0						12.100	mg	163624.0703	37770.63				
supplier	Au Plating	Gold (Au)	7440-57-5						1.210	mg	16362.40703	3777.06				
DAF (2300)	M-011 Other inorganic materials	0.447	mg					supplier	Glue	Silver (Ag)	7440-22-4		0.416	mg	930000	1297.66
								supplier	Glue	Tetramethylene dimethacrylate	2082-81-7		0.029	mg	65000	90.70
								supplier	Glue	Difunctional Acrylic Esters	Proprietary		0.002	mg	5000	6.98
Bonding Wires (Cu)	Other inorganic materials	1.546	mg	supplier	BONDING WIRE	Copper	7440-50-8		1.500	mg	970500	4682.78				
				supplier	BONDING WIRE	Palladium	7440-05-3		0.043	mg	28000	135.10				
				supplier	BONDING WIRE	Gold	7440-57-5		0.002	mg	1500	7.24				
Solderballs (SAC105)	M-011 Other inorganic materials	37.081	mg	supplier	Solderball	Tin (Sn)	7440-31-5		36.525	mg	985000	114013.56				
				supplier	Solderball	Silver (Ag)	7440-22-4		0.371	mg	10000	1157.50				
				supplier	Solderball	Copper (Cu)	7440-50-8		0.185	mg	5000	578.75				
Encapsulation (G770FE)	Other organic materials	198.943	mg	supplier	MOLDING COMPOUND	Epoxy Resin A	Proprietary		5.968	mg	30000	18630.25				
				supplier	MOLDING COMPOUND	Epoxy Resin B	1675-54-3		5.968	mg	30000	18630.25				
				supplier	MOLDING COMPOUND	Phenol Resin	Proprietary		9.151	mg	46000	28566.39				
				supplier	MOLDING COMPOUND	Silica(Amorphous) A	60676-86-0		144.035	mg	724000	449610.10				
				supplier	MOLDING COMPOUND	Silica(Amorphous) B	7631-86-9		29.841	mg	150000	93151.26				
				supplier	MOLDING COMPOUND	Aluminum Hydroxide	21645-51-2		2.984	mg	15000	9315.13				
supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		0.995	mg	5000	3105.04								